

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

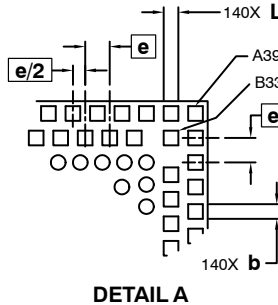
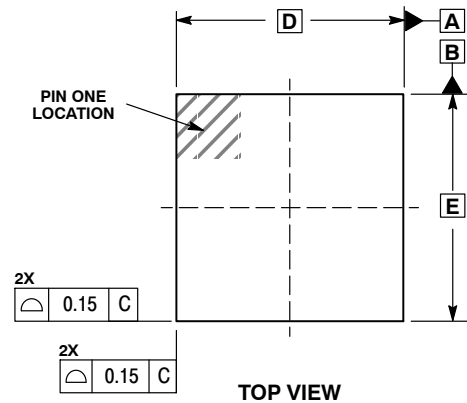


TLLGA140 10x10, 0.5P, Dual-Row, Staggered-Pad CASE 513AL-01 ISSUE O

DATE 20 OCT 2009



SCALE 1:1

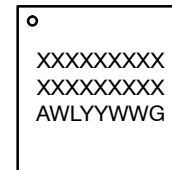


NOTES:

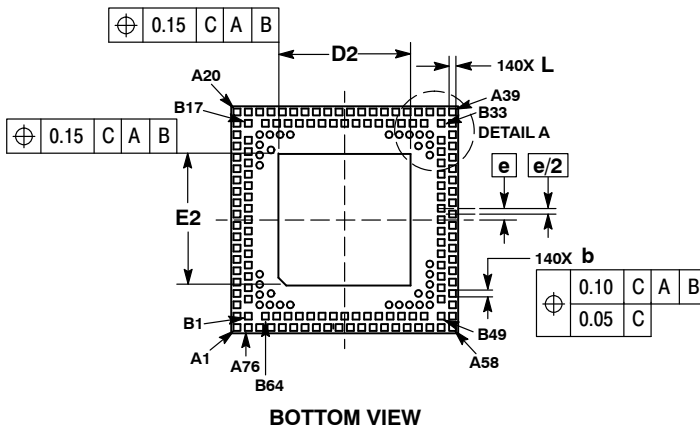
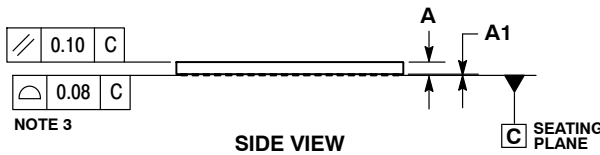
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.50	0.60
A1	---	0.05
b	0.25	0.35
D	10.00	BSC
D2	5.70	5.90
E	10.00	BSC
E2	5.70	5.90
e	0.50	BSC
L	0.25	0.35

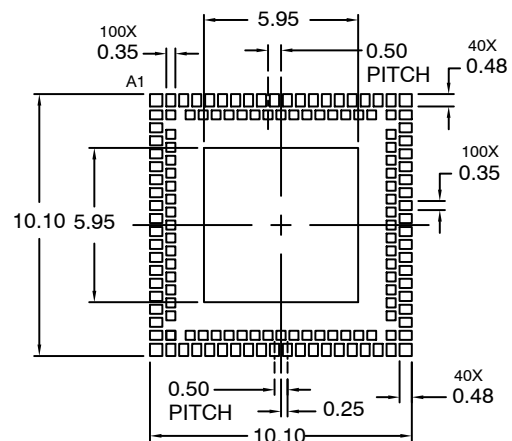
GENERIC MARKING DIAGRAM



- XXXXX = Device Code
- A = Assembly Site
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package



RECOMMENDED SOLDERING FOOTPRINT*



DIMENSION: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	TLLGA140, 10X10, 0.5P	PAGE 1 OF 2

